L	Hits	Search Text	DB	Time stamp
Number				
3	2	"200018353"	JPO; DERWENT	2003/09/15
4	69536	((substrate or board or carrier) with	USPAT;	2003/09/15
1		(land or pad))	US-PGPUB;	12:51
[ļ		EPO; JPO;	
	1		DERWENT; IBM TDB	
5			USPAT;	2003/09/15
) "			US-PGPUB;	12:52
1	1		EPO; JPO;	
1	l		DERWENT; IBM TDB	
6	11872	(((substrate or board or carrier) with	USPAT:	2003/09/15
*		(land or pad))) and ((cavity or recess or	US-PGPUB;	12:55
	}	via or trench) with (land or pad))	EPO; JPO;	i i
			DERWENT;	
7	3108	((((substrate or board or carrier) with	IBM_TDB USPAT;	2003/09/15
ļ ' l	3100	(land or pad))) and ((cavity or recess or	US-PGPUB;	13:57
		via or trench) with (land or pad))) and	EPO; JPO;	1
		((slit or gap or hole or space) with	DERWENT;	l l
8	3007	(land or pad)) ((((substrate or board or carrier) with	IBM_TDB USPAT;	2003/09/15
°	3007	((((Substrate or board or carrier) with (land or pad))) and ((cavity or recess or	US-PGPUB;	13:46
		via or trench) with (land or pad))) and	EPO; JPO;	
		((solder or ball or bump) with (land or	DERWENT;	
9	1795	pad)) ((((substrate or board or carrier) with	IBM_TDB USPAT;	2003/09/15
) "	1/93	((((((substrate of board of carrier) with (land or pad))) and ((cavity or recess or	US-PGPUB;	13:45
)		via or trench) with (land or pad))) and	EPO; JPO;	15.15
1		((solder or ball or bump) with (land or	DERWENT;	
10	583	pad))) and (@ad<20000312)	IBM_TDB USPAT;	2003/09/15
10	383	((((substrate or board or carrier) with (land or pad))) and ((cavity or recess or	US-PGPUB;	13:55
	1	via or trench) with (land or pad))) and	EPO; JPO;	15705
		((slit or gap or hole or space) with (air	DERWENT;	1
		or escape or moisture or vent or bubbles))	IBM_TDB	
11	322	(((((substrate or board or carrier) with	USPAT;	2003/09/15
		(land or pad))) and ((cavity or recess or	US-PGPUB;	14:03
		via or trench) with (land or pad))) and	EPO; JPO;	
	(((slit or gap or hole or space) with (air	DERWENT; IBM TDB	!
		or escape or moisture or vent or bubbles))) and (@ad<20000312)	I DIT I DE	!
12	108	((((((substrate or board or carrier) with	USPAT;	2003/09/15
		(land or pad))) and ((cavity or recess or	US-PGPUB;	13:47
		via or trench with (land or pad))) and	EPO; JPO;	
]		((slit or gap or hole or space) With (air or escape or moisture or vent or	DERWENT; IBM TDB	
]		bubbles))) and (@ad<20000312)) and		
		((solder or ball or bump or reflow) with	1	l i
	7	(land or pad))		
13	′	("4664962" "5315072" "5404044" "5406034" "5541368" "5689091"	USPAT	2003/09/15
		"5783865").PN.		13.33
14	2	5962922.URPN.	USPAT	2003/09/15
15	1002	(13:53
12	1002	(pad or land) with ((air or escape or moisture or vent or bubbles) and (reflow	USPAT; US-PGPUB;	2003/09/15 13:57
		or solder or ball or bump))	EPO; JPO;	1
			DERWENT;	
			IBM_TDB	
16	326	((pad or land) with ((air or escape or moisture or vent or bubbles) and (reflow	USPAT; US-PGPUB;	2003/09/15
		or solder or ball or bump))) and ((slit	EPO; JPO;	14.00
		or gap or hole or space) with (land or	DERWENT;	
		pad))	IBM TDB	ll

17	219	(((pad or land) with ((air or escape or	USPAT:	2003/09/15	ī
1,	245		US-PGPUB;	14:03	L
		or solder or ball or bump))) and ((slit	EPO; JPO;	14.03	ŀ
		or gap or hole or space) with (land or	DERWENT;		ı
		pad))) and (@ad<20000312)	IBM TDB		ļ
	_				1
18	3	6028366.URPN.	USPAT	2003/09/15	l
				14:05	1